

Board Level Cooling – Extruded 5012



BOARD LEVEL COOLING - EXTRUDED 5012

Extruded 5012 is a rectangular bi-directional board level heat sink designed to cool DIP devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
501200B00000G	DIP



HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Epoxy
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	18.57
Heat Sink Length (mm)	6.35
Heat Sink Height (mm)	4.83
Heat Sink Mounting Direction	Horizontal

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

